

MEG01-004

Serial number 09/837,007

TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

From : George O. Saile (Reg. No. 19,572)
20 McIntosh Drive
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Date: July 20, 2002

REF: APPLICANT : Mou-Shiung Lin
SERIAL NO. : 09/837,007
ART UNIT : 2827
FILING DATE : 04/18/01
ATT'Y NO. : MEG01-004
EXAMINER : Mitchell, James M.
TITLE : A STRUCTURE AND MANUFACTURING
METHOD OF A CHIP SCALE PACKAGE

AMENDMENT AND RESPONSE TO OFFICE ACTION

Sir:

In response to an office action mailed on 07/05/02
please consider the following amendments and remarks with
respect to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal service as First
Class mail in an envelop addressed to the Commissioner of
Patents and Trademarks, Washington, D.C. 20231, on
August 21, 2002.

Stephen B. Ackerman (Reg. No 37,761)

[Signature]

Signature

8/21/02

Date